

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Reissue Application)	
of U.S. Patent No. 6,329,275)	
Issue Date: December 11, 2001)	Group Art Unit: 2822
)	
First Named Inventor: Takashi Ishigami)	Examiner: Potter, Roy Karl
)	
Application No. 10/732,888)	
)	
Reissue Filing Date: December 10, 2003)	Confirmation No. 6183
)	
For: INTERCONNECTOR LINE OF)	
THIN FILM, SPUTTER TARGET)	
FOR FORMING THE WIRING)	
FILM AND ELECTRONIC)	
COMPONENT USING THE SAME)	

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.97(c)

Pursuant to 37 C.F.R. §§ 1.56 and 1.97(c), Applicants bring to the attention of the Examiner the documents listed on the attached PTO/SB/08 form. Applicants file this Information Disclosure Statement (IDS) after the period set forth in 37 C.F.R. § 1.97(b), but before the mailing date of either a Final action, Quayle action, or a Notice of Allowance, to the undersigned representative's knowledge at the time of filing this IDS. Under the provisions of 37 C.F.R. § 1.97(c), this Information Disclosure Statement is accompanied by a fee of \$180.00 as specified by Section 1.17(p).

Applicants attach a copy of a Japanese Patent Office Action received in counterpart Japanese application no. 2004-076172. The Examiner of the Japanese Patent Office rejected the claims in JP 2004-076172 as being unpatentable over JP-A Hei 07-45555 (KOKAI), JP-A Hei 04-323872 (KOKAI), JP-A Hei 05-211147 (KOKAI), JP-A Hei 01-289140 (KOKAI), JP-A Hei 01-134426 (KOKAI), JP-A Sho 62-240738 (KOKAI), JP-A Sho 62-235454 (KOKAI), and JP-A Hei 05-171434. Japanese Publication Nos. JP-A 07-45555, JP-A 62-240738, JP-A 62-235454, and JP-A 05-171434, cited in the Japanese Patent Office Action, are not being listed or attached since they were previously submitted during prosecution of U.S. Patent No. 6,329,275. Applicants attach copies of the remaining listed documents. Applicants respectfully request that the Examiner consider the listed documents and indicate their consideration by making appropriate notation on the attached form.

In lieu of a statement of relevance or full translation of the non-English documents JP-A Hei 04-323872, JP-A Hei 05-211147, JP-A Hei 01-289140, and JP-A Hei 01-134426, Applicants enclose an English language Abstract for each of these documents. Applicants also provide the following remarks regarding the listed non-English language documents:

1. JP-A Hei 04-323872 discloses a constituent material for a semiconductor device. The constituent material for a semiconductor device is formed of an Al based alloy containing 0.05 to 1.0 at% of at least one element selected from the group of Mn, Cr, and Zr. The Al based alloy film has excellent heat resistance (stress-migration resistance), electro-migration resistance, and corrosion resistance.

2. JP-A Hei 05-211147 discloses an Al wiring. The Al wiring is formed of an Al based alloy containing 0.01 to 0.5 wt% of Sc. The Al wiring has excellent stress-migration resistance.

3. JP-A Hei 01-289140 discloses an Al alloy wiring. The Al alloy wiring is formed on an Al alloy containing at least one element selected from the group of lanthanoid elements, Y, and Sc, or an Al alloy containing B and at least one element selected from the group of lanthanoid elements, Y, and Sc.

4. JP-A Hei 01-134426 discloses a thin-film transistor. The thin-film transistor includes gate lines and data lines. The gate lines or data lines have an Al alloy containing 0.005 to 1 wt% of at least one element selected from the group of Pd, Mg, Li, Be, Mn, Fe, Co, Ni, Cu, La, and Ce.

This submission does not represent that a search has been made or that no better art exists and does not constitute an admission that the listed documents are material or constitute "prior art." If the Examiner applies any or all of the documents as prior art against any claim in the application and Applicants determine that the cited documents do not constitute "prior art" under United States law, Applicants reserve the right to present the relevant facts and law to the Office regarding the appropriate status of such documents.

Applicants further reserve the right to take appropriate action to establish the patentability of the disclosed invention over the listed documents, should any or all of the documents be applied against the claims of the present application.

If there is any fee due in connection with the filing of this Statement, please charge the fee to our Deposit Account No. 06-0916.

Respectfully submitted,

FINNEGAN, HENDERSON, FARABOW,
GARRETT, & DUNNER, L.L.P.

By: 

David M. Longo
Reg. No. 53,235

Dated: April 30, 2008